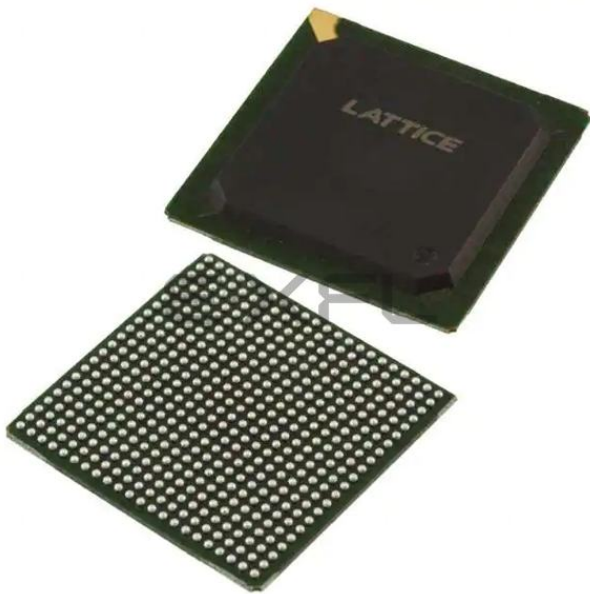




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15400
Total RAM Bits	358400
Number of I/O	352
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec15e-5fn484c

Introduction

The LatticeECP/EC family of FPGA devices is optimized to deliver mainstream FPGA features at low cost. For maximum performance and value, the LatticeECP™ (Economy Plus) FPGA concept combines an efficient FPGA fabric with high-speed dedicated functions. Lattice's first family to implement this approach is the LatticeECP-DSP™ (Economy Plus DSP) family, providing dedicated high-performance DSP blocks on-chip. The LatticeEC™ (Economy) family supports all the general purpose features of LatticeECP devices without dedicated function blocks to achieve lower cost solutions.

The LatticeECP/EC FPGA fabric, which was designed from the outset with low cost in mind, contains all the critical FPGA elements: LUT-based logic, distributed and embedded memory, PLLs and support for mainstream I/Os. Dedicated DDR memory interface logic is also included to support this memory that is becoming increasingly prevalent in cost-sensitive applications.

The ispLEVER® design tool suite from Lattice allows large complex designs to be efficiently implemented using the LatticeECP/EC FPGA family. Synthesis library support for LatticeECP/EC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP/EC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeECP/EC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

grammed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-11. PLL Diagram

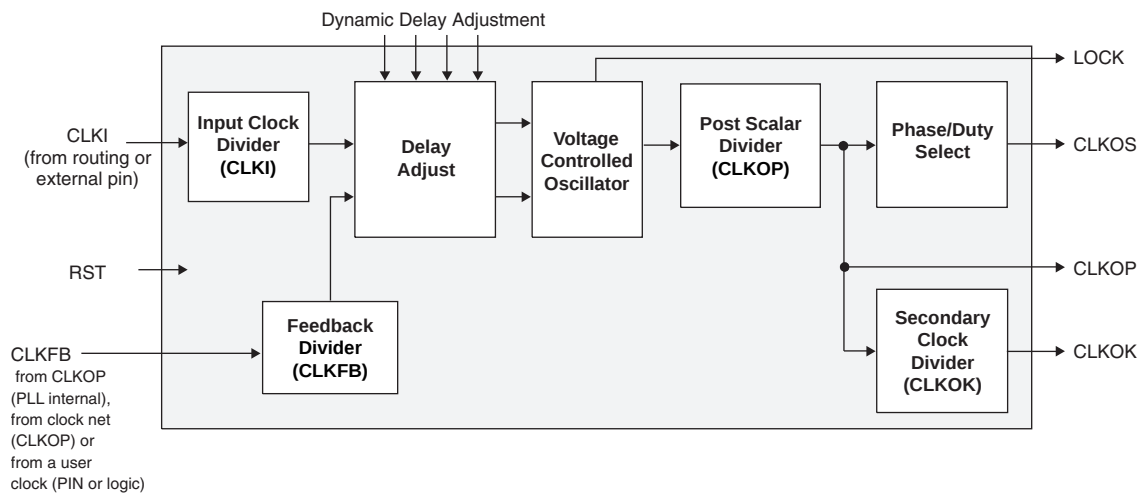


Figure 2-12 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-12. PLL Primitive

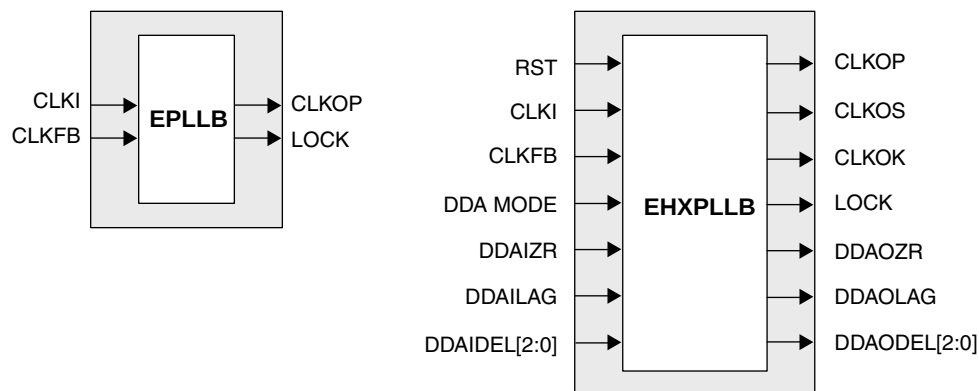
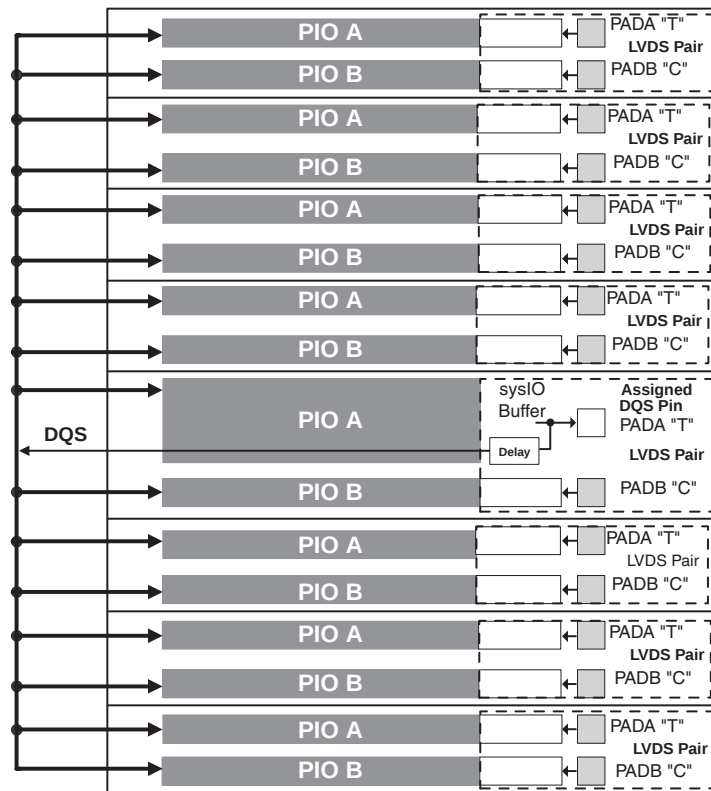


Table 2-12. PIO Signal List

Name	Type	Description
CE0, CE1	Control from the core	Clock enables for input and output block FFs.
CLK0, CLK1	Control from the core	System clocks for input and output blocks.
LSR	Control from the core	Local Set/Reset.
GSRN	Control from routing	Global Set/Reset (active low).
INCK	Input to the core	Input to Primary Clock Network or PLL reference inputs.
DQS	Input to PIO	DQS signal from logic (routing) to PIO.
INDD	Input to the core	Unregistered data input to core.
INFF	Input to the core	Registered input on positive edge of the clock (CLK0).
IPOS0, IPOS1	Input to the core	DDR _X registered inputs to the core.
ONEG0	Control from the core	Output signals from the core for SDR and DDR operation.
OPOS0,	Control from the core	Output signals from the core for DDR operation
OPOS1 ONEG1	Tristate control from the core	Signals to Tristate Register block for DDR operation.
TD	Tristate control from the core	Tristate signal from the core used in SDR operation.
DDRCLKPOL	Control from clock polarity bus	Controls the polarity of the clock (CLK0) that feed the DDR input block.

Figure 2-25. DQS Routing



PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for both single data rate (SDR) and double data rate (DDR) operation along with the necessary clock and selection logic. Programmable delay lines used to shift incoming clock and data signals are also included in these blocks.

Figure 2-27. Input Register DDR Waveforms

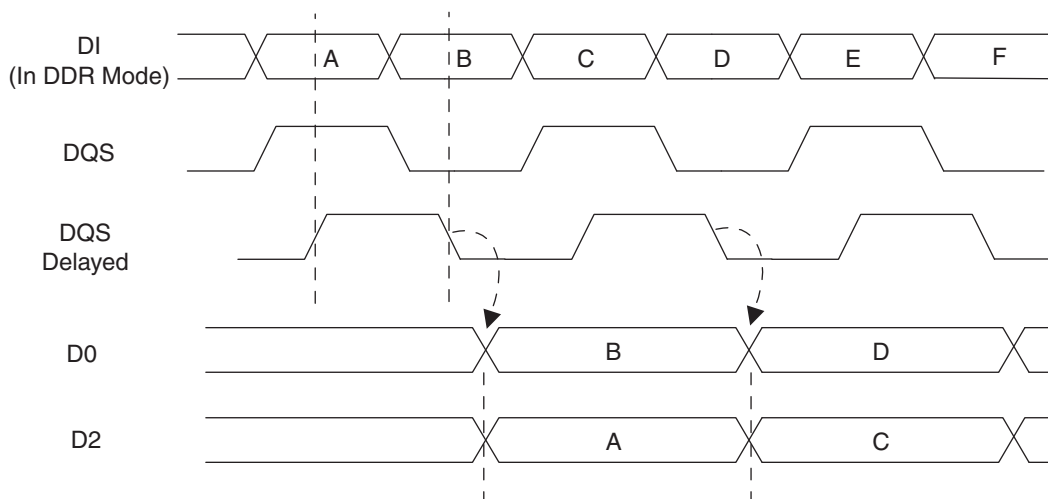
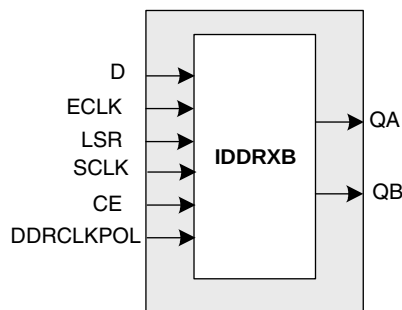


Figure 2-28. INDDRxB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysI/O buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-29 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-30 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Table 2-14. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Nom.)
Single-ended Interfaces		
LVTTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVC MOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 16mA, 20mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 16mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS ¹	N/A	2.5
LVPECL ¹	N/A	3.3
RSDS ¹	N/A	2.5

1. Emulated with external resistors.

Hot Socketing

The LatticeECP/EC devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled within specified limits, this allows for easy integration with the rest of the system. These capabilities make the LatticeECP/EC ideal for many multiple power supply and hot-swap applications.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeECP/EC devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP/EC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2 class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL18 class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
HSTL15 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8
HSTL18 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18 class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL18 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

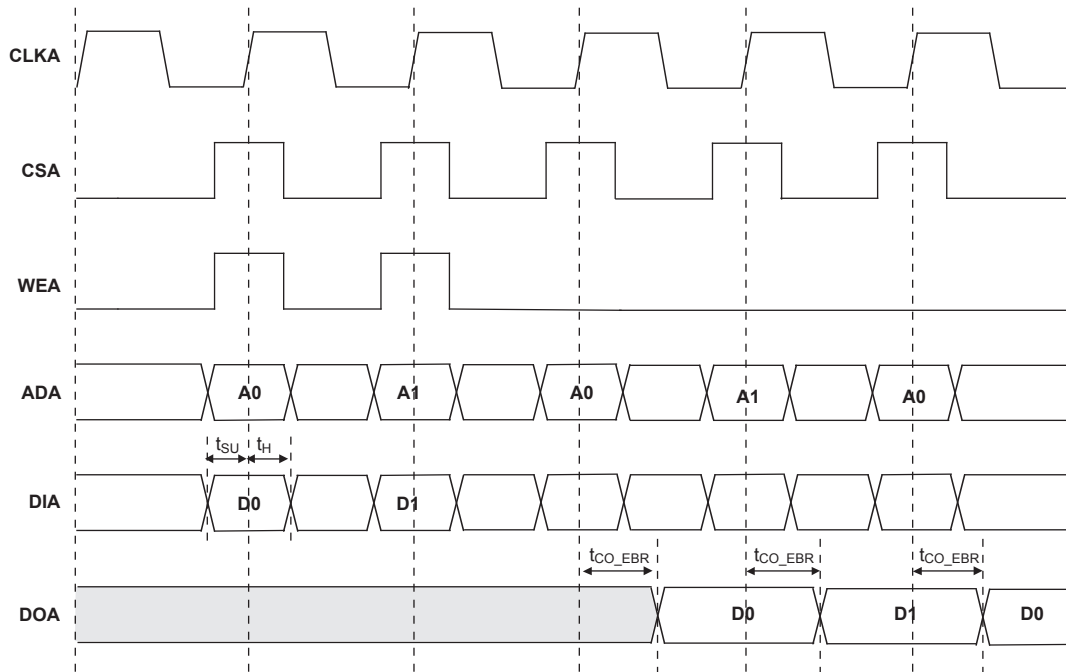
LatticeECP/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL) ¹									
t _{CO} ⁷	Clock to Output - PIO Output Register	LFEC1	—	5.09	—	6.11	—	7.13	ns
		LFEC3	—	5.71	—	6.85	—	7.99	ns
		LFEC6	—	5.60	—	6.72	—	7.84	ns
		LFEC10	—	5.47	—	6.57	—	7.66	ns
		LFEC15	—	5.67	—	6.81	—	7.94	ns
		LFEC20	—	5.89	—	7.07	—	8.25	ns
		LFEC33	—	6.19	—	7.42	—	8.66	ns
t _{SU} ⁷	Clock to Data Setup - PIO Input Register	LFEC1	-0.08	—	-0.10	—	-0.12	—	ns
		LFEC3	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC6	-0.63	—	-0.76	—	-0.89	—	ns
		LFEC10	-0.43	—	-0.52	—	-0.61	—	ns
		LFEC15	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC20	-0.88	—	-1.06	—	-1.24	—	ns
		LFEC33	-1.12	—	-1.34	—	-1.56	—	ns
t _H ⁷	Clock to Data Hold - PIO Input Register	LFEC1	2.19	—	2.62	—	3.06	—	ns
		LFEC3	2.80	—	3.36	—	3.92	—	ns
		LFEC6	2.69	—	3.23	—	3.77	—	ns
		LFEC10	2.56	—	3.08	—	3.59	—	ns
		LFEC15	2.76	—	3.32	—	3.87	—	ns
		LFEC20	2.99	—	3.58	—	4.18	—	ns
		LFEC33	3.28	—	3.93	—	4.59	—	ns
t _{SU_DEL} ⁷	Clock to Data Setup - PIO Input Register with Data Input Delay	LFEC1	3.36	—	4.03	—	4.70	—	ns
		LFEC3	2.74	—	3.29	—	3.84	—	ns
		LFEC6	2.81	—	3.37	—	3.93	—	ns
		LFEC10	3.01	—	3.61	—	4.21	—	ns
		LFEC15	2.74	—	3.29	—	3.83	—	ns
		LFEC20	2.56	—	3.07	—	3.58	—	ns
		LFEC33	2.32	—	2.79	—	3.25	—	ns
t _{H_DEL} ⁷	Clock to Data Hold - PIO Input Register with Input Data Delay	LFEC1	-1.31	—	-1.57	—	-1.83	—	ns
		LFEC3	-0.70	—	-0.83	—	-0.97	—	ns
		LFEC6	-0.80	—	-0.96	—	-1.12	—	ns
		LFEC10	-0.93	—	-1.12	—	-1.30	—	ns
		LFEC15	-0.73	—	-0.88	—	-1.02	—	ns
		LFEC20	-0.51	—	-0.61	—	-0.71	—	ns
		LFEC33	-0.22	—	-0.26	—	-0.30	—	ns
f _{MAX_IO} ²	Clock Frequency of I/O and PFU Register	All	—	420	—	378	—	340	Mhz
DDR I/O Pin Parameters ^{3, 4, 5}									
t _{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t _{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI

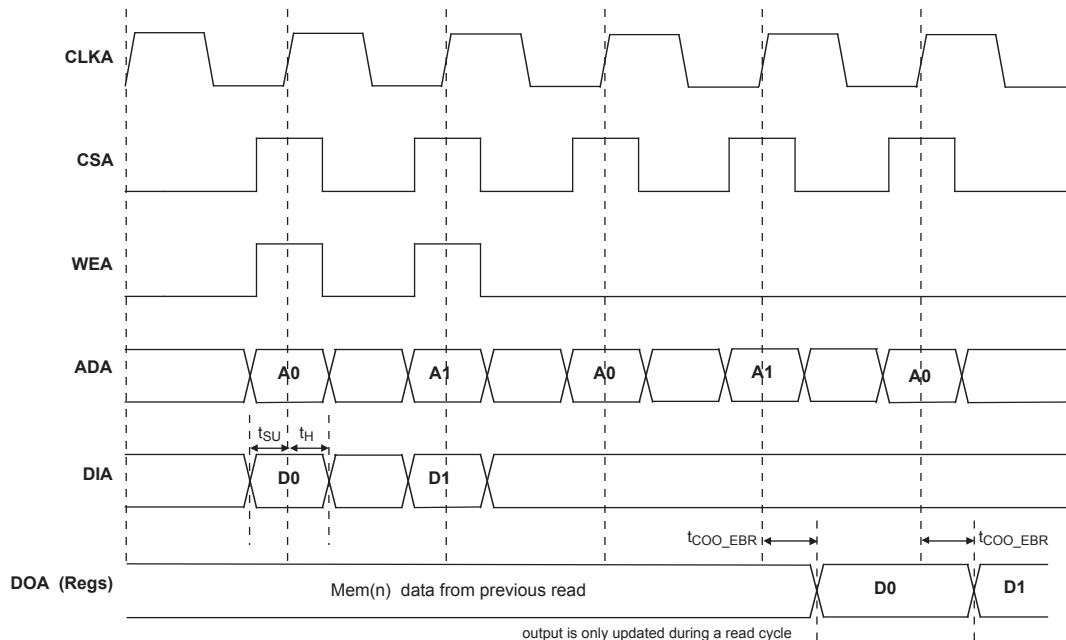
EBR Memory Timing Diagrams

Figure 3-8. Read/Write Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Figure 3-9. Read/Write Mode with Input and Output Registers





LatticeECP/EC Family Data Sheet

Pinout Information

September 2012

Data Sheet

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user-programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal (active low). Any I/O pin can be GSRN.
NC	—	No connect.
GND	—	Ground. Dedicated pins.
V _{CC}	—	Power supply pins for core logic. Dedicated pins.
V _{CCAUX}	—	Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	Power supply pins for I/O bank x. Dedicated pins.
V _{REF1_x} , V _{REF2_x}	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V _{REF} inputs. When not used, they may be used as I/O pins.
XRES	—	10K ohm +/-1% resistor must be connected between this pad and ground.
V _{CCPLL}	—	Power supply pin for PLL. Applicable to ECP/EC33 device.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	I	Reference clock (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_PLL[T, C]_FB_A	I	Optional feedback (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
PCLK[T, C]_[n:0]_[3:0]	I	Primary Clock pads, T = true and C = complement, n per side, indexed by bank and 0,1,2,3 within bank.
[LOC]DQS[num]	I	DQS input pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = ball function number. Any pad can be configured to be output.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine. Pull-up is enabled during configuration.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine. No pull-up enabled.

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Signal Descriptions (Cont.)

Signal Name	I/O	Description
TDI	I	Test Data in pin. Used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence). Pull-up is enabled during configuration.
TDO	O	Output pin. Test Data out pin used to shift data out of device using 1149.1.
V _{CCJ}	—	V _{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[2:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled. These are dedicated pins.
INITN	I/O	Open Drain pin. Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. It is a dedicated pin.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up. This is a dedicated pin.
DONE	I/O	Open Drain pin. Indicates that the configuration sequence is complete, and the startup sequence is in progress. This is a dedicated pin.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY/SISPI	I/O	Read control command in SPI3 or SPIX mode.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled.
CS1N	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled.
WRITEN	I	Write Data on Parallel port (Active low).
D[7:0]/SPID[0:7]	I/O	sysCONFIG Port Data I/O.
DOUT/CSO	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port.
DI/CSSPIN	I/O	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. Output when used in SPI/SPIX modes.

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1*	GND0 GND7	-			GND0 GND7	-		
2	VCCIO7	7			VCCIO7	7		
3	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
4	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
5	NC	-			NC	-		
6	NC	-			NC	-		
7	NC	-			PL3B	7		
8	NC	-			PL4A	7	T	
9	NC	-			PL4B	7	C	
10	NC	-			PL5A	7	T	
11	NC	-			PL5B	7	C	
12	NC	-			PL6A	7	T	LDQS6
13	NC	-			VCCIO7	7		
14	NC	-			PL6B	7	C	
15	PL3A	7	T		PL7A	7	T	
16	PL3B	7	C		PL7B	7	C	
17	PL4A	7	T		PL8A	7	T	
18	NC	-			NC	-		
19	PL4B	7	C		PL8B	7	C	
20	PL5A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
21	PL5B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
22	NC	-			VCCAUX	-		
23	XRES	6			XRES	6		
24	NC	-			NC	-		
25	NC	-			NC	-		
26	VCC	-			VCC	-		
27	TCK	6			TCK	6		
28	GND	-			GND	-		
29	TDI	6			TDI	6		
30	TMS	6			TMS	6		
31	TDO	6			TDO	6		
32	VCCJ	6			VCCJ	6		
33	PL7A	6	T	LLM0_PLLT_IN_A	PL11A	6	T	LLM0_PLLT_IN_A
34	PL7B	6	C	LLM0_PLLC_IN_A	PL11B	6	C	LLM0_PLLC_IN_A
35	PL8A	6	T	LLM0_PLLT_FB_A	PL12A	6	T	LLM0_PLLT_FB_A
36	PL8B	6	C	LLM0_PLLC_FB_A	PL12B	6	C	LLM0_PLLC_FB_A
37	VCCIO6	6			VCCIO6	6		
38	PL9A	6	T		PL13A	6	T	
39	PL9B	6	C		PL13B	6	C	
40	PL10A	6	T		PL14A	6	T	
41	GND6	6			GND6	6		
42	PL10B	6	C		PL14B	6	C	

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
K2	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
K1	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
L2	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
L1	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
M2	PL13A	6	T		PL22A	6	T	
M1	PL13B	6	C		PL22B	6	C	
N1	PL14A	6	T		PL23A	6	T	
GND	GND6	6			GND6	6		
N2	PL14B	6	C		PL23B	6	C	
M4	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
M3	PL15B	6	C		PL24B	6	C	
P1	PL16A	6	T		PL25A	6	T	
R1	PL16B	6	C		PL25B	6	C	
P2	PL17A	6	T		PL26A	6	T	
P3	PL17B	6	C		PL26B	6	C	
N3	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
N4	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
GND	GND6	6			GND6	6		
GND	GND5	5			GND5	5		
P4	PB2A	5	T		PB2A	5	T	
N5	PB2B	5	C		PB2B	5	C	
P5	PB3A	5	T		PB3A	5	T	
P6	PB3B	5	C		PB3B	5	C	
R4	PB4A	5	T		PB4A	5	T	
R3	PB4B	5	C		PB4B	5	C	
T2	PB5A	5	T		PB5A	5	T	
T3	PB5B	5	C		PB5B	5	C	
R5	PB6A	5	T	BDQS6	PB6A	5	T	BDQS6
R6	PB6B	5	C		PB6B	5	C	
T4	PB7A	5	T		PB7A	5	T	
T5	PB7B	5	C		PB7B	5	C	
N6	PB8A	5	T		PB8A	5	T	
M6	PB8B	5	C		PB8B	5	C	
T6	PB9A	5	T		PB9A	5	T	
GND	GND5	5			GND5	5		
T7	PB9B	5	C		PB9B	5	C	
P7	PB10A	5	T		PB10A	5	T	
N7	PB10B	5	C		PB10B	5	C	
R7	PB11A	5	T		PB11A	5	T	
R8	PB11B	5	C		PB11B	5	C	
M7	PB12A	5	T		PB12A	5	T	
M8	PB12B	5	C		PB12B	5	C	
T8	PB13A	5	T		PB13A	5	T	

LFEC10/EC10 and LFEC15/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC10/LFEC10				LFEC15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
G9	GND	-			GND	-		
H10	GND	-			GND	-		
H7	GND	-			GND	-		
H8	GND	-			GND	-		
H9	GND	-			GND	-		
J10	GND	-			GND	-		
J7	GND	-			GND	-		
J8	GND	-			GND	-		
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K7	GND	-			GND	-		
K8	GND	-			GND	-		
K9	GND	-			GND	-		
T1	GND	-			GND	-		
T16	GND	-			GND	-		
E12	VCC	-			VCC	-		
E5	VCC	-			VCC	-		
E8	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M5	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
B15	VCCAUX	-			VCCAUX	-		
R2	VCCAUX	-			VCCAUX	-		
F7	VCCIO0	0			VCCIO0	0		
F8	VCCIO0	0			VCCIO0	0		
F10	VCCIO1	1			VCCIO1	1		
F9	VCCIO1	1			VCCIO1	1		
G11	VCCIO2	2			VCCIO2	2		
H11	VCCIO2	2			VCCIO2	2		
J11	VCCIO3	3			VCCIO3	3		
K11	VCCIO3	3			VCCIO3	3		
L10	VCCIO4	4			VCCIO4	4		
L9	VCCIO4	4			VCCIO4	4		
L7	VCCIO5	5			VCCIO5	5		
L8	VCCIO5	5			VCCIO5	5		
J6	VCCIO6	6			VCCIO6	6		
K6	VCCIO6	6			VCCIO6	6		
G6	VCCIO7	7			VCCIO7	7		
H6	VCCIO7	7			VCCIO7	7		
F6	VCC	-			VCC	-		
F11	VCC	-			VCC	-		
L11	VCC	-			VCC	-		
L6	VCC	-			VCC	-		

LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
A17	PT47A	1	T		A17	PT47A	1	T	
B15	PT46B	1	C		B15	PT46B	1	C	
A16	PT46A	1	T	TDQS46	A16	PT46A	1	T	TDQS46
A15	PT45B	1	C		A15	PT45B	1	C	
GND	GND1	1			GND	GND1	1		
A14	PT45A	1	T		A14	PT45A	1	T	
G14	PT44B	1	C		G14	PT44B	1	C	
E15	PT44A	1	T		E15	PT44A	1	T	
D15	PT43B	1	C		D15	PT43B	1	C	
C15	PT43A	1	T		C15	PT43A	1	T	
C14	PT42B	1	C		C14	PT42B	1	C	
B14	PT42A	1	T		B14	PT42A	1	T	
A13	PT41B	1	C		A13	PT41B	1	C	
GND	GND1	1			GND	GND1	1		
B13	PT41A	1	T		B13	PT41A	1	T	
E14	PT40B	1	C		E14	PT40B	1	C	
C13	PT40A	1	T		C13	PT40A	1	T	
F14	PT39B	1	C		F14	PT39B	1	C	
D14	PT39A	1	T		D14	PT39A	1	T	
E13	PT38B	1	C		E13	PT38B	1	C	
G13	PT38A	1	T	TDQS38	G13	PT38A	1	T	TDQS38
A12	PT37B	1	C		A12	PT37B	1	C	
GND	GND1	1			GND	GND1	1		
B12	PT37A	1	T		B12	PT37A	1	T	
F13	PT36B	1	C		F13	PT36B	1	C	
D13	PT36A	1	T		D13	PT36A	1	T	
F12	PT35B	1	C	VREF2_1	F12	PT35B	1	C	VREF2_1
D12	PT35A	1	T	VREF1_1	D12	PT35A	1	T	VREF1_1
F11	PT34B	1	C		F11	PT34B	1	C	
C12	PT34A	1	T		C12	PT34A	1	T	
A11	PT33B	0	C	PCLKC0_0	A11	PT33B	0	C	PCLKC0_0
GND	GND0	0			GND	GND0	0		
A10	PT33A	0	T	PCLKT0_0	A10	PT33A	0	T	PCLKT0_0
E12	PT32B	0	C	VREF1_0	E12	PT32B	0	C	VREF1_0
E11	PT32A	0	T	VREF2_0	E11	PT32A	0	T	VREF2_0
B11	PT31B	0	C		B11	PT31B	0	C	
C11	PT31A	0	T		C11	PT31A	0	T	
B9	PT30B	0	C		B9	PT30B	0	C	
B10	PT30A	0	T	TDQS30	B10	PT30A	0	T	TDQS30
A9	PT29B	0	C		A9	PT29B	0	C	
GND	GND0	0			GND	GND0	0		
A8	PT29A	0	T		A8	PT29A	0	T	
D11	PT28B	0	C		D11	PT28B	0	C	
C10	PT28A	0	T		C10	PT28A	0	T	

LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
A7	PT27B	0	C		A7	PT27B	0	C	
A6	PT27A	0	T		A6	PT27A	0	T	
B7	PT26B	0	C		B7	PT26B	0	C	
B8	PT26A	0	T		B8	PT26A	0	T	
A5	PT25B	0	C		A5	PT25B	0	C	
GND	GND0	0			GND	GND0	0		
B6	PT25A	0	T		B6	PT25A	0	T	
G10	PT24B	0	C		G10	PT24B	0	C	
E10	PT24A	0	T		E10	PT24A	0	T	
F10	PT23B	0	C		F10	PT23B	0	C	
D10	PT23A	0	T		D10	PT23A	0	T	
G9	PT22B	0	C		G9	PT22B	0	C	
E9	PT22A	0	T	TDQS22	E9	PT22A	0	T	TDQS22
C9	PT21B	0	C		C9	PT21B	0	C	
GND	GND0	0			GND	GND0	0		
C8	PT21A	0	T		C8	PT21A	0	T	
F9	PT20B	0	C		F9	PT20B	0	C	
D9	PT20A	0	T		D9	PT20A	0	T	
F8	PT19B	0	C		F8	PT19B	0	C	
D7	PT19A	0	T		D7	PT19A	0	T	
D8	PT18B	0	C		D8	PT18B	0	C	
C7	PT18A	0	T		C7	PT18A	0	T	
GND	GND0	0			GND	GND0	0		
A4	PT17B	0	C		A4	PT17B	0	C	
B4	PT17A	0	T		B4	PT17A	0	T	
C4	PT16B	0	C		C4	PT16B	0	C	
C5	PT16A	0	T		C5	PT16A	0	T	
D6	PT15B	0	C		D6	PT15B	0	C	
B5	PT15A	0	T		B5	PT15A	0	T	
E6	PT14B	0	C		E6	PT14B	0	C	
C6	PT14A	0	T	TDQS14	C6	PT14A	0	T	TDQS14
A3	PT13B	0	C		A3	PT13B	0	C	
GND	GND0	0			GND	GND0	0		
B3	PT13A	0	T		B3	PT13A	0	T	
F6	PT12B	0	C		F6	PT12B	0	C	
D5	PT12A	0	T		D5	PT12A	0	T	
F7	PT11B	0	C		F7	PT11B	0	C	
E8	PT11A	0	T		E8	PT11A	0	T	
G6	PT10B	0	C		G6	PT10B	0	C	
E7	PT10A	0	T		E7	PT10A	0	T	
GND	GND0	0			GND	GND0	0		
GND	GND0	0			GND	GND0	0		
A1	GND	-			A1	GND	-		
A22	GND	-			A22	GND	-		

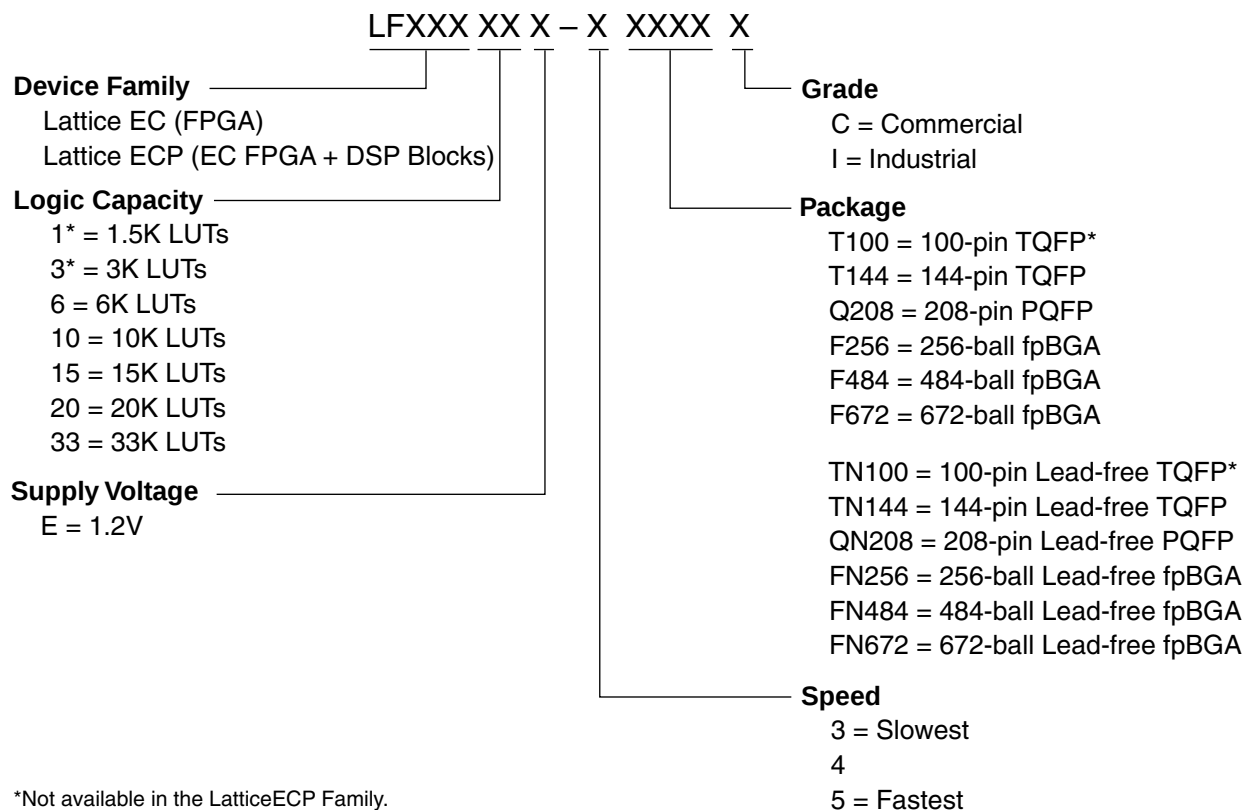
LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
AB1	GND	-			AB1	GND	-		
AB22	GND	-			AB22	GND	-		
H15	GND	-			H15	GND	-		
H8	GND	-			H8	GND	-		
J10	GND	-			J10	GND	-		
J11	GND	-			J11	GND	-		
J12	GND	-			J12	GND	-		
J13	GND	-			J13	GND	-		
J14	GND	-			J14	GND	-		
J9	GND	-			J9	GND	-		
K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-		
K9	GND	-			K9	GND	-		
L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-		
L9	GND	-			L9	GND	-		
M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-		
M9	GND	-			M9	GND	-		
N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-		
N13	GND	-			N13	GND	-		
N14	GND	-			N14	GND	-		
N9	GND	-			N9	GND	-		
P10	GND	-			P10	GND	-		
P11	GND	-			P11	GND	-		
P12	GND	-			P12	GND	-		
P13	GND	-			P13	GND	-		
P14	GND	-			P14	GND	-		
P9	GND	-			P9	GND	-		
R15	GND	-			R15	GND	-		
R8	GND	-			R8	GND	-		
J16	VCC	-			J16	VCC	-		
J7	VCC	-			J7	VCC	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

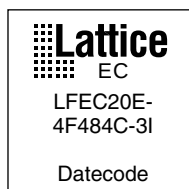
LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
U21	PR36B	3	C		U21	PR48B	3	C	
T21	PR36A	3	T	RDQS36	T21	PR48A	3	T	RDQS48
T25	PR35B	3	C		T25	PR47B	3	C	
GND	GND3	3			GND	GND3	3		
T26	PR35A	3	T		T26	PR47A	3	T	
T22	PR34B	3	C		T22	PR46B	3	C	
T23	PR34A	3	T		T23	PR46A	3	T	
T24	PR33B	3	C		T24	PR45B	3	C	
R23	PR33A	3	T		R23	PR45A	3	T	
R25	PR32B	3	C		R25	PR44B	3	C	
R24	PR32A	3	T		R24	PR44A	3	T	
R26	PR31B	3	C		R26	PR43B	3	C	
GND	GND3	3			GND	GND3	3		
P26	PR31A	3	T		P26	PR43A	3	T	
R21	PR30B	3	C		R21	PR42B	3	C	
R22	PR30A	3	T		R22	PR42A	3	T	
P25	PR29B	3	C		P25	PR41B	3	C	
P24	PR29A	3	T		P24	PR41A	3	T	
P23	PR28B	3	C		P23	PR40B	3	C	
P22	PR28A	3	T	RDQS28	P22	PR40A	3	T	RDQS40
N26	PR27B	3	C		N26	PR39B	3	C	
GND	GND3	3			GND	GND3	3		
M26	PR27A	3	T		M26	PR39A	3	T	
N21	PR26B	3	C		N21	PR38B	3	C	
P21	PR26A	3	T		P21	PR38A	3	T	
N23	PR25B	3	C		N23	PR37B	3	C	
N22	PR25A	3	T		N22	PR37A	3	T	
N25	PR24B	3	C		N25	PR36B	3	C	
N24	PR24A	3	T		N24	PR36A	3	T	
L26	PR22B	2	C	PCLKC2_0	L26	PR34B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2		
K26	PR22A	2	T	PCLKT2_0	K26	PR34A	2	T	PCLKT2_0
M22	PR21B	2	C		M22	PR33B	2	C	
M23	PR21A	2	T		M23	PR33A	2	T	
M25	PR20B	2	C		M25	PR32B	2	C	
M24	PR20A	2	T		M24	PR32A	2	T	
M21	PR19B	2	C		M21	PR31B	2	C	
L21	PR19A	2	T	RDQS19	L21	PR31A	2	T	RDQS31
L22	PR18B	2	C		L22	PR30B	2	C	
GND	GND2	2			GND	GND2	2		
L23	PR18A	2	T		L23	PR30A	2	T	
L25	PR17B	2	C		L25	PR29B	2	C	

Part Number Description



Ordering Information

Note: LatticeECP/EC devices are dual marked. For example, the commercial speed grade LFEC20E-4F484C is also marked with industrial grade -3I (LFEC20E-3F484I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:



LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN484C	360	-3	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-4FN484C	360	-4	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-5FN484C	360	-5	Lead-Free fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC1E-3QN208I	112	-3	Lead-Free PQFP	208	IND	1.5K
LFEC1E-4QN208I	112	-4	Lead-Free PQFP	208	IND	1.5K
LFEC1E-3TN144I	97	-3	Lead-Free TQFP	144	IND	1.5K
LFEC1E-4TN144I	97	-4	Lead-Free TQFP	144	IND	1.5K
LFEC1E-3TN100I	67	-3	Lead-Free TQFP	100	IND	1.5K
LFEC1E-4TN100I	67	-4	Lead-Free TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC3E-3FN256I	160	-3	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-4FN256I	160	-4	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-3QN208I	145	-3	Lead-Free PQFP	208	IND	3.1K
LFEC3E-4QN208I	145	-4	Lead-Free PQFP	208	IND	3.1K
LFEC3E-3TN144I	97	-3	Lead-Free TQFP	144	IND	3.1K
LFEC3E-4TN144I	97	-4	Lead-Free TQFP	144	IND	3.1K
LFEC3E-3TN100I	67	-3	Lead-Free TQFP	100	IND	3.1K
LFEC3E-4TN100I	67	-4	Lead-Free TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K

Date	Version	Section	Change Summary
December 2004	01.4	Architecture	Updated Hot Socketing Recommended Power Up Sequence section.
		Pinout Information	Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Pin Information
			Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Power Supply and NC Connections
			Added LFEC1 and LFEC3 100 TQFP Pinout
			Added LFEC1 and LFEC3 144 TQFP Pinout
			Added LFEC1, LFEC3 and LFECP/EC10 208 PQFP Pinout
			Added LFEC3, LFECP/EC10 and LFECP/EC15 256 fpBGA Pinout
			Added LFECP/EC10 and LFECP/EC15 484 fpBGA Pinout
		Ordering Information	Added Lead-Free Package Designators
			Added Lead-Free Ordering Part Numbers
		Supplemental Information	Updated list of technical notes.
April 2005	01.5	Architecture	EBR memory support section has been updated with clarification.
			Updated sysIO buffer pair section.
		DC & Switching Characteristics	Hot Socketing Specification has been updated.
			DC Electrical Characteristics table (I_{IL} , I_{IH}) has been updated.
			Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			External Switching Characteristics section has been updated.
			Removed t_{RSTW} spec. from PLL Parameter table.
			t_{RST} specifications have been updated.
			sysCONFIG Port Timing Specifications (t_{BSCL} , t_{ODISS} , t_{PRGMRJ}) have been updated.
		Pinout Information	Added LFECP/EC33 Pinout Information
			Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
			484-fpBGA logic connection has been updated (Ball # J6, J17, P6 and P17 for ECP/EC33 are now called VCCPLL).
			672-fpBGA logic connection has been updated (Ball # K19, L8, U19, U8 for ECP/EC33 are now called VCCPLL).
May 2005	01.6	Introduction	ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.
		Architecture	Table 2-10 has been updated (ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.)
			Recommended Power Up Sequence section has been removed.
		DC & Switching Characteristics	Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			Vos test condition has been updated to $(VOP+VOM)/2$.
			Register-to-Register performance table has been updated (rev. G 0.27).
			External switching characteristics have been updated (rev. G 0.27).
			Internal timing parameters have been updated (rev. G 0.27).
			Timing adders have been updated (rev. G 0.27).
			sysCONFIG port timing specifications have been updated.
		Pinout Information	Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	OPN list has been updated.